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For: RF PACKAGE

ABSTRACT OF DISCLOSURE

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A novel package includes a substrate including an upper surface ground plane connected to a lower surface ground plane by vias through the substrate, a die located on the upper ground plane and including a die pad, a transmission path including, on the upper surface of the substrate, a bonding pad connected to a first transmission line itself connected to a transition pad, and on the lower surface of the substrate, a second transmission line connected to the transition pad by a via through the substrate. A wire bond extends from the bonding pad to the die pad. A portion of the upper surface ground plane and the lower surface ground plane are connected by vias defining opposing walls on either side of the transmission path for signal isolation. A low pass filter for compensating wire bond inductance includes: a first capacitance formed between the bonding pad and at least the lower surface ground plane, the wire bond inductance, and a second capacitance formed between the die pad and at least the upper surface ground plane.